1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±25	V
I_D	Drain current (continuous) at T_C = 25 °C	72	A
	Drain current (continuous) at T_C = 100 °C	45	A
I_{DM}(1)	Drain current (pulsed)	288	A
P_{TOT}	Total power dissipation at T_C = 25 °C	446	W
dv/dt(2)	Peak diode recovery voltage slope	15	V/ns
dv/dt(3)	MOSFET dv/dt ruggedness	100	
T_{stg}	Storage temperature range	-55 to 150	°C
T_J	Operating junction temperature range		

1. *Pulse width is limited by safe operating area.*
2. *I_{SD} ≤ 72 A, di/dt = 400 A/µs, $V_{DS(peak)}$ < $V_{(BR)DSS}$, V_{DD} = 400 V*
3. *V_{DS} ≤ 480 V*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	0.28	°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient	50	°C/W

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{Jmax})	11	A
E_{AS}	Single pulse avalanche energy (starting T_J = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	1.4	J

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 4. On /off-states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	600			V
I_{DSS}	Zero-gate voltage drain current	V_{GS} = 0 V, V_{DS}= 600 V			1	µA
		V_{GS} = 0 V, V_{DS} = 600 V, T_C = 125 °C(1)			100	
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = ±25 V			±5	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	3.25	4	4.75	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 36 A		32	36	mΩ

1. *Defined by design, not subject to production test.*

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{GS} = 0 V, V_{DS} = 100 V, f = 1 MHz	-	4850	-	pF
C_{oss}	Output capacitance		-	380	-	pF
C_{rss}	Reverse transfer capacitance		-	3.5	-	pF
$C_{oss\ eq.}$ (1)	Equivalent output capacitance	V_{GS} = 0 V, V_{DS} = 0 to 480 V	-	851	-	pF
R_G	Intrinsic gate resistance	f = 1 MHz open drain	-	1.5	-	Ω
Q_g	Total gate charge	V_{DD} = 480 V, I_D = 72 A, V_{GS} = 0 to 10 V (see Figure 14. Test circuit for gate charge behavior)	-	106	-	nC
Q_{gs}	Gate-source charge		-	32	-	nC
Q_{gd}	Gate-drain charge		-	45	-	nC

1. *$C_{oss\ eq.}$ is defined as the constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.*

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d\ (on)}$	Turn-on delay time	V_{DD} = 300 V, I_D = 36 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	35	-	ns
t_r	Rise time		-	38	-	ns
$t_{d(off)}$	Turn-off delay time		-	90	-	ns
t_f	Fall time		-	12	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		72	A
I_{SDM} (1)	Source-drain current (pulsed)		-		288	A
V_{SD} (2)	Forward on voltage	V_{GS} = 0 V, I_{SD} = 72 A	-		1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 72 A, di/dt = 100 A/µs,	-	367		ns
Q_{rr}	Reverse recovery charge	V_{DD} = 60 V (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	6.4		µC
I_{RRM}	Reverse recovery current		-	35		A
t_{rr}	Reverse recovery time	I_{SD} = 72 A, di/dt = 100 A/µs,	-	552		ns
Q_{rr}	Reverse recovery charge	V_{DD} = 60 V, T_J = 150 °C	-	13.7		µC
I_{RRM}	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	49.6		A

1. *Pulse width is limited by safe operating area.*
2. *Pulse test: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

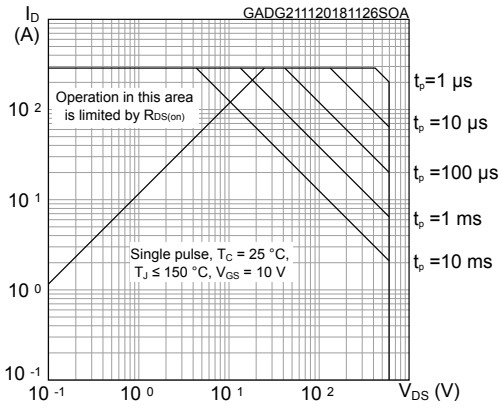


Figure 2. Thermal impedance

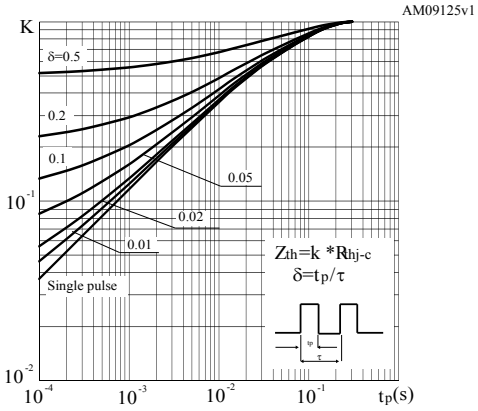


Figure 3. Output characteristics

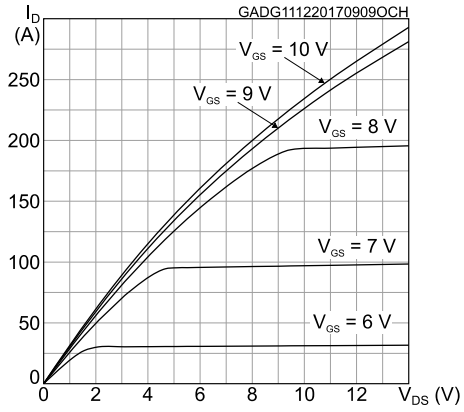


Figure 4. Transfer characteristics

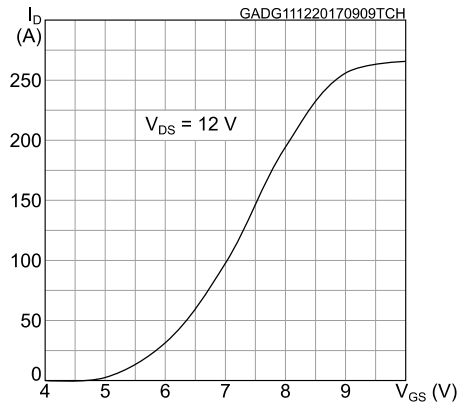


Figure 5. Gate charge vs gate-source voltage

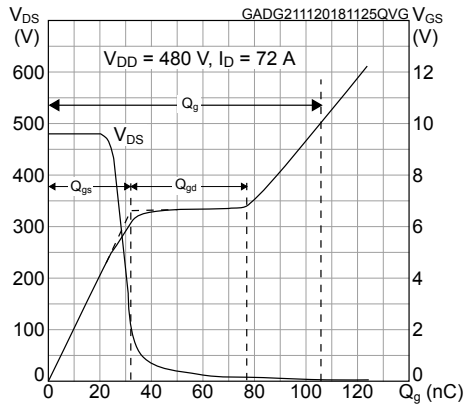


Figure 6. Static drain-source on-resistance

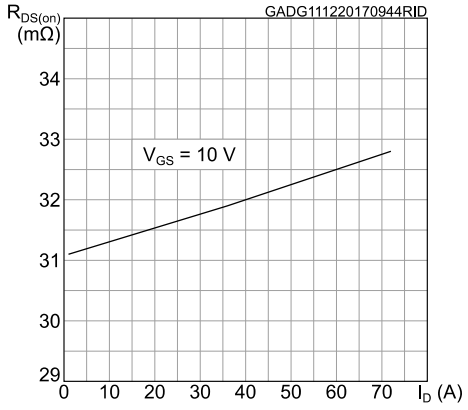


Figure 7. Normalized on-resistance vs temperature

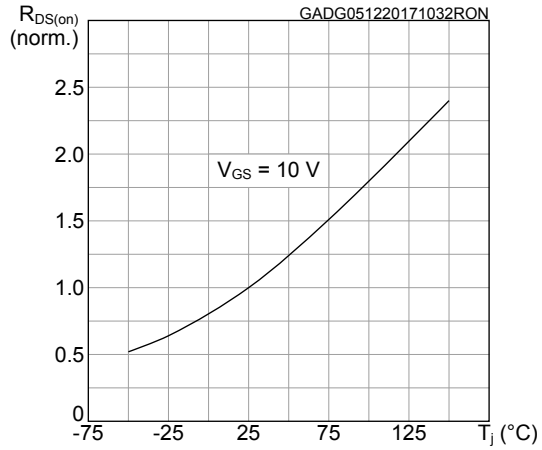


Figure 8. Normalized $V_{(BR)DSS}$ vs temperature

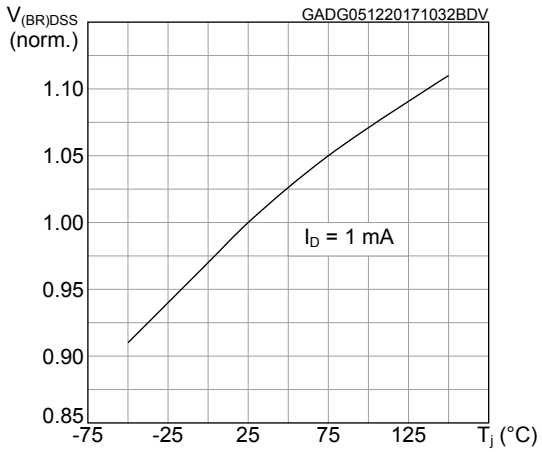


Figure 9. Capacitance variations

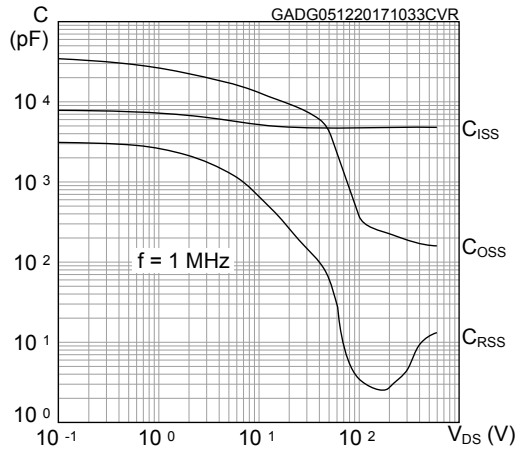


Figure 10. Normalized gate threshold voltage vs temperature

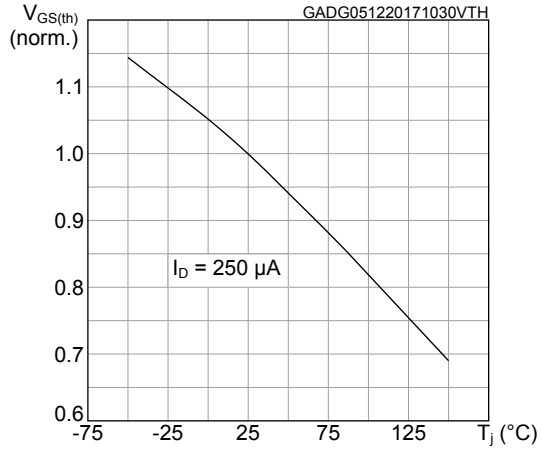


Figure 11. Output capacitance stored energy

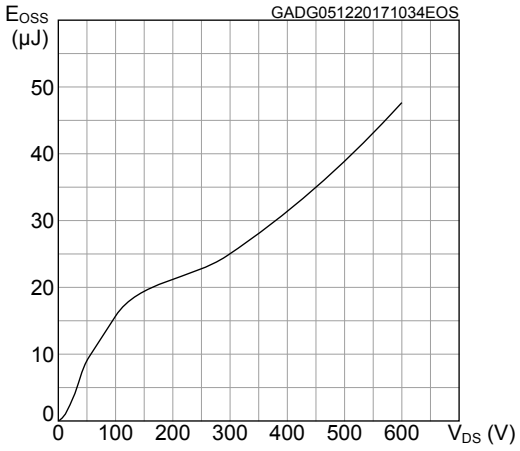
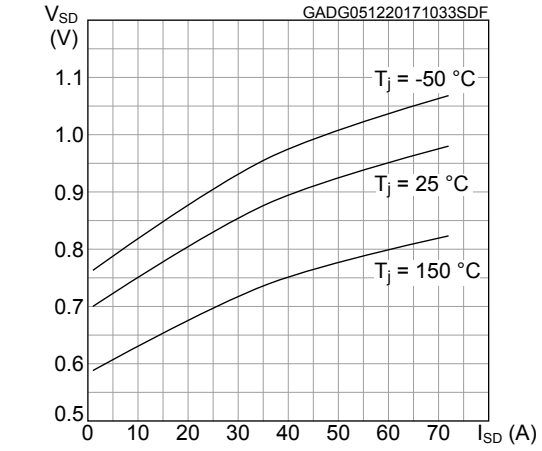


Figure 12. Source-drain diode forward characteristics



3 Test circuits

Figure 13. Test circuit for resistive load switching times

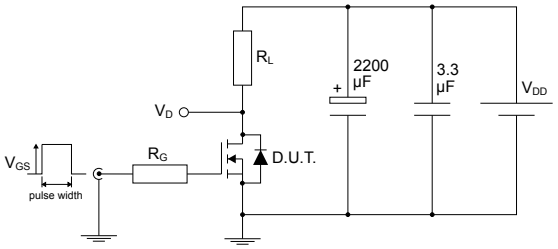


Figure 14. Test circuit for gate charge behavior

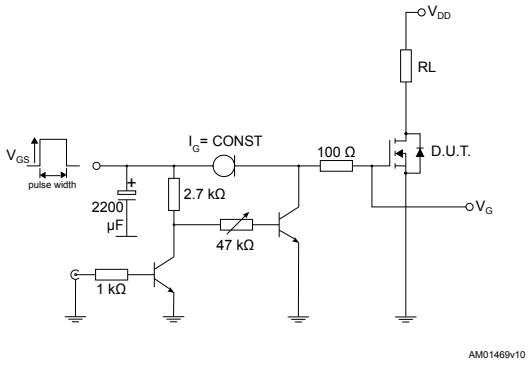


Figure 15. Test circuit for inductive load switching and diode recovery times

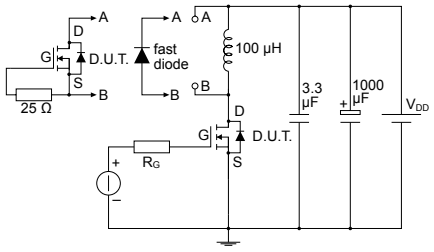


Figure 16. Unclamped inductive load test circuit

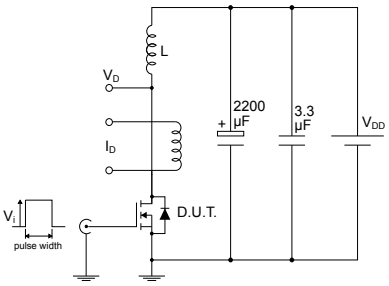


Figure 17. Unclamped inductive waveform

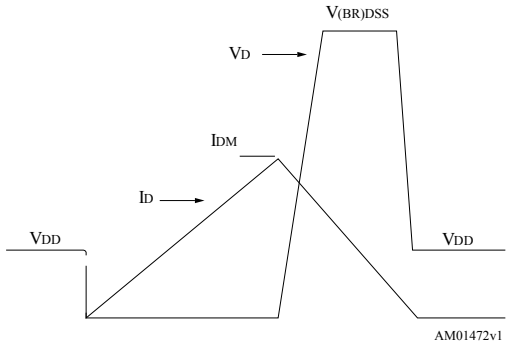
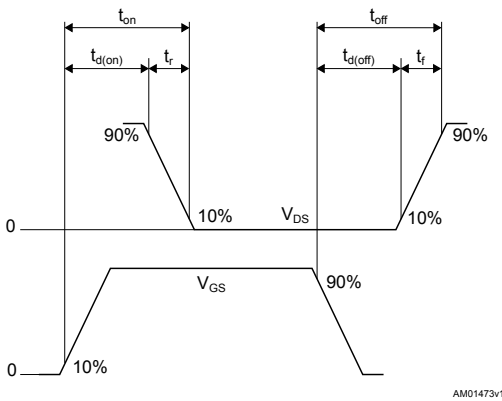


Figure 18. Switching time waveform

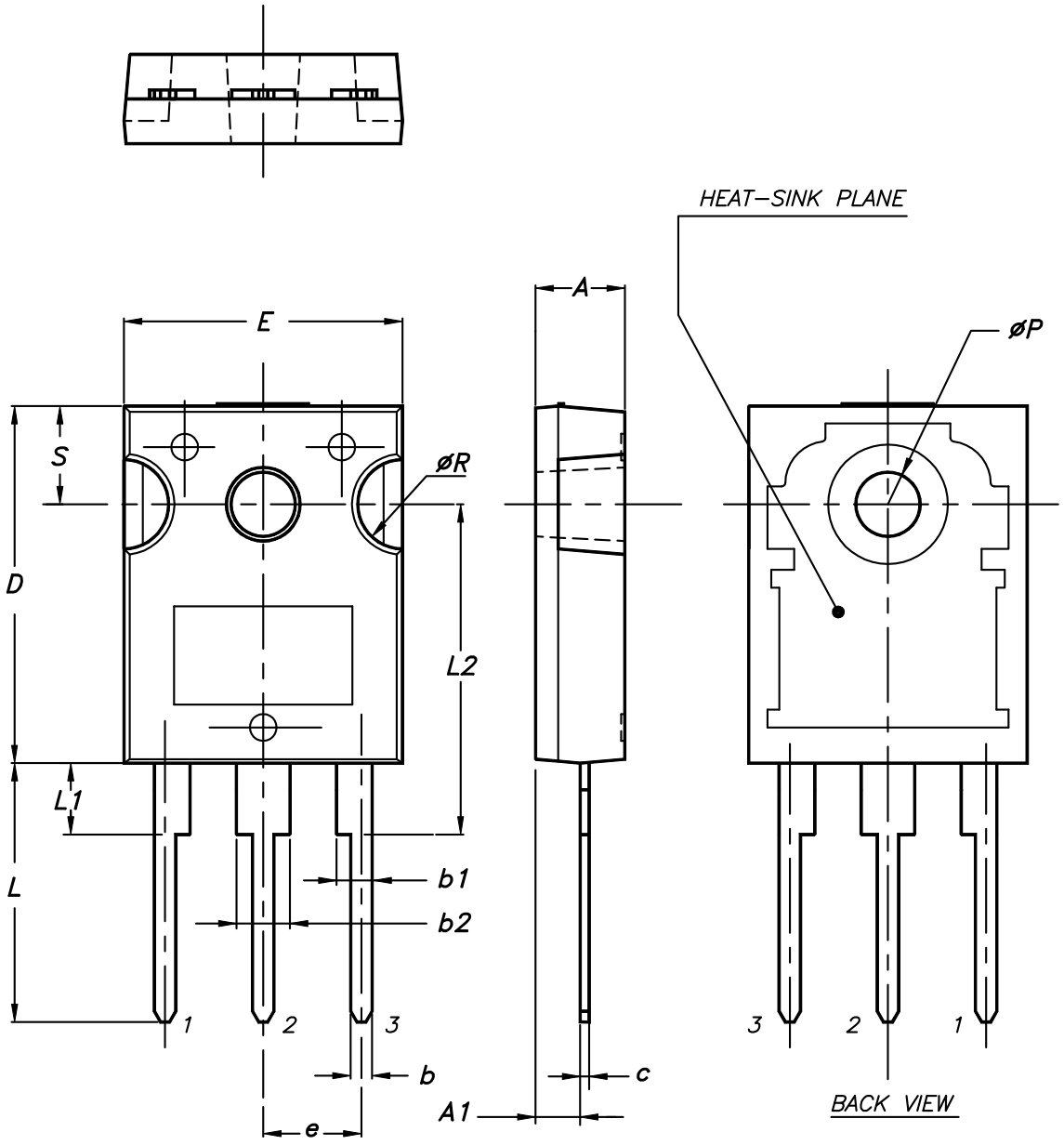


4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 TO-247 package information

Figure 19. TO-247 package outline



0075325_9

Table 8. **TO-247 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

Revision history

Table 9. **Document revision history**

Date	Revision	Changes
11-Dec-2017	1	Initial version
22-Nov-2018	2	Updated Table 5. Dynamic. Updated Figure 1. Safe operating area, Figure 5. Gate charge vs gate-source voltage, Figure 9. Capacitance variations and Figure 14. Test circuit for gate charge behavior. Minor text changes

Contents